

PCN Number:	20140414001	PCN Date:	4/14/2014
Title:	Design Revision (for Select TMP708/709 Devices)		
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037
		Dept:	Quality Services
Proposed 1st Ship Date:	10/14/2014	Estimated Sample Availability:	Date provided at sample request
Change Type:	<input checked="" type="checkbox"/> Design		

PCN Details

Description of Change:

This notification is to inform of a design revision for select TMP708/709 devices. This design change does not affect the device's guaranteed datasheet specifications or electrical performance. The affected devices are listed in the "Product Affected" section.

The table below describes changes that were made:

Description of Change	Benefit of Change
Revision of die to eliminate startup issue.	Improve reliability

Reason for Change:

Improve reliability

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):




None

Changes to product identification resulting from this PCN:

Die Rev designator will change as shown in table & sample label below:

Current	New
Die Rev [2P]	Die Rev [2P]
A	B

Sample product shipping label to indicate die rev location (**not actual product label**)

 <p>MADE IN: Malaysia 2DC: 2Q:</p> <table border="1"> <tr> <td>MSL '2 /260C/1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 /235C/UNLIM</td> <td>03/29/04</td> </tr> </table> <p>OPT: ITEM: 39 LBL: 5A (L)T0:1750</p>	MSL '2 /260C/1 YEAR	SEAL DT	MSL 1 /235C/UNLIM	03/29/04			<p>(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS</p>
MSL '2 /260C/1 YEAR	SEAL DT						
MSL 1 /235C/UNLIM	03/29/04						

Product Affected:			
TMP708AIDBV	TMP708AIDBVT	TMP709AIDBVR	TMP709AIDBVT
TMP708AIDBVR	TMP709AIDBV		
Qualification Data: Approved 4/10/2014			
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.			
Qual Device: TMP708AIDBV			
Package/Die Construction Details			
Assembly Site:	NFME	# Pins-Designator, Family:	5-DBV, SOT
Fab Process:	50HPA07	Die Revision:	B
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results			
Reliability Test	Conditions	Sample Size (PASS/FAIL)	
Electrical Characterization, side by side	Per Datasheet Parameters	Pass	
ESD HBM	1000V	3/0	
ESD CDM	250V	3/0	
Latch-up	Per JESD78	6/0	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or to your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com